

# **A Digitally Enhanced 1.8-V 15-b 40-Msample/s CMOS Pipelined ADC**

Eric Siragusa<sup>1</sup> and Ian Galton

University of California,  
San Diego

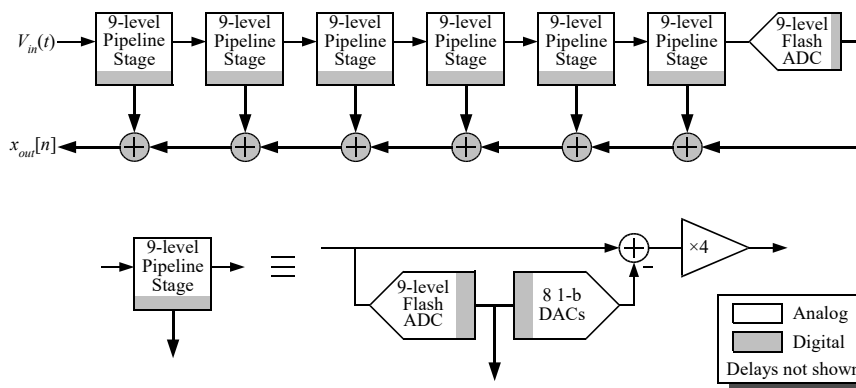
<sup>1</sup> Now with Analog Devices, San Diego, California

## **Outline**

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- Conventional PADC Example
- Digitally Enhanced PADC Prototype
- System-Level Design Details
- Circuit-Level Design Details
- Measured Results
- Conclusion

## A Conventional Pipelined ADC Example



- Seven stages
- Each resolves slightly more than 3 bits
- 1-b of redundancy per stage
- Ideal DACs and gains  $\Rightarrow$  accuracy is just over 15b

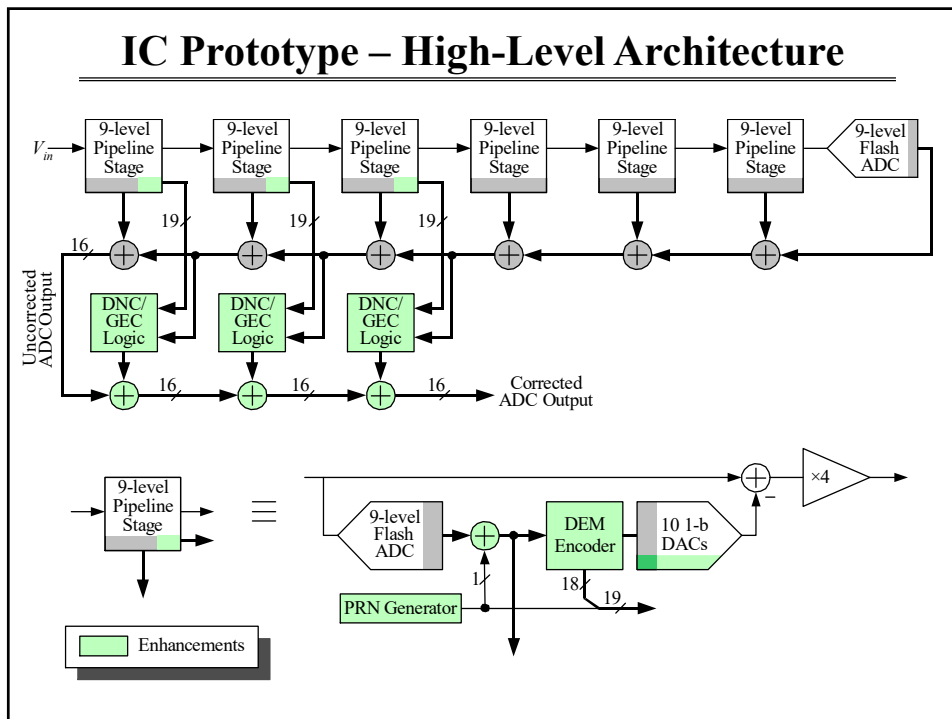
## Conventional Switched Capacitor PADC

- **Interstage gain error:**
  - *Sources:* capacitor mismatch, finite open-loop amplifier gain, incomplete amplifier settling
  - *Effect:* “leakage” of quantization noise into PADC output
- **DAC Noise:**
  - *Source:* capacitor mismatch
  - *Effect:* introduction of signal-dependent errors
- **Conventional solutions:**
  - Large capacitors, high-gain op-amps
  - Foreground calibration techniques
  - Analog-intensive calibration techniques
  - Trimming

## Digitally Enhanced PADC Prototype

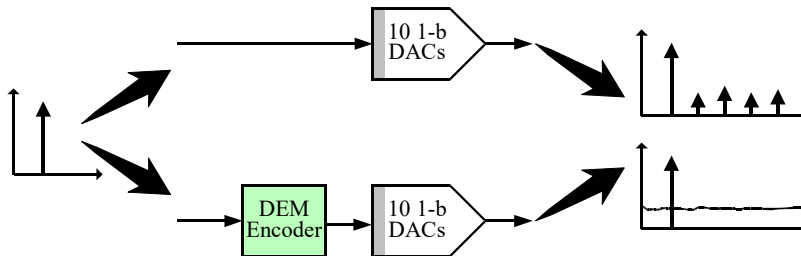
- **Analog performance limitations are mitigated by background digital signal processing:**
  - Gain error correction (GEC) <sup>1</sup>
  - DAC noise cancellation (DNC) <sup>2</sup>
  - Segmented mismatch-scrambling DACs <sup>3</sup>
- **Demonstrated in a 0.18  $\mu\text{m}$  CMOS prototype:**
  - 1.8 V, 15 bit, 40 Msamples/s, 400 mW
  - 90 dB SFDR, 72 dB peak SNR, 88 dB THD

1. E. J. Siragusa, I Galton, *IEE Electronics Letters*, March 30, 2000
2. I. Galton, *IEEE TCAS-II*, March, 2000
3. A. Fishov, E. Siragusa, J. Welz, E. Fogleman, I. Galton, *IEEE ISCAS*, May 2002.



## Dynamic Element Matching Overview

When DAC mismatches are present:

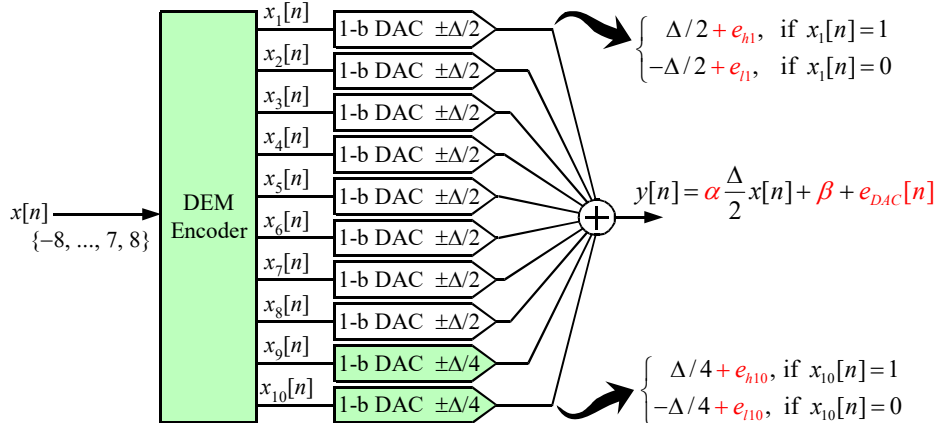


- DEM alone improves SFDR ...but not SNDR!

However DEM causes the noise to have “structure”:

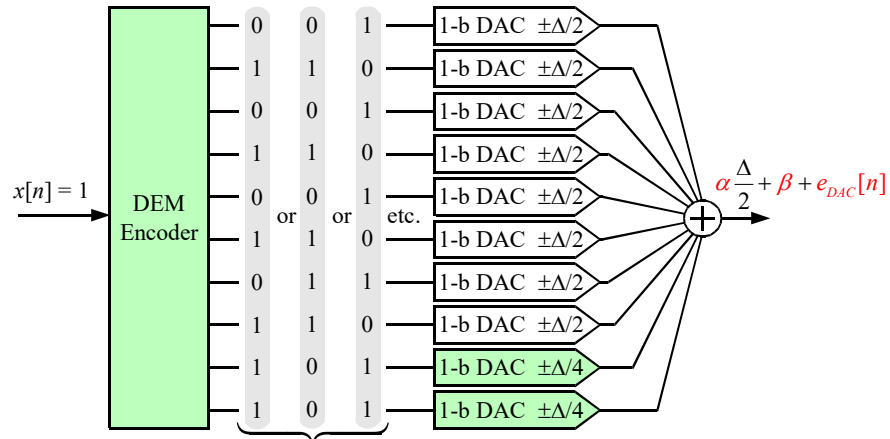
- Noise was “manipulated” with known pseudo-random sequences and digital logic in the encoder
- DNC technique will exploit the structure to remove the noise

## Dynamic Element Matching DAC



DEM Encoder uses pseudo-randomization to convert 1-b DAC mismatches,  $e_{hi}$  and  $e_{li}$ , into a constant gain,  $\alpha$ , a constant offset,  $\beta$ , and *white* DAC noise,  $e_{DAC}[n]$ .

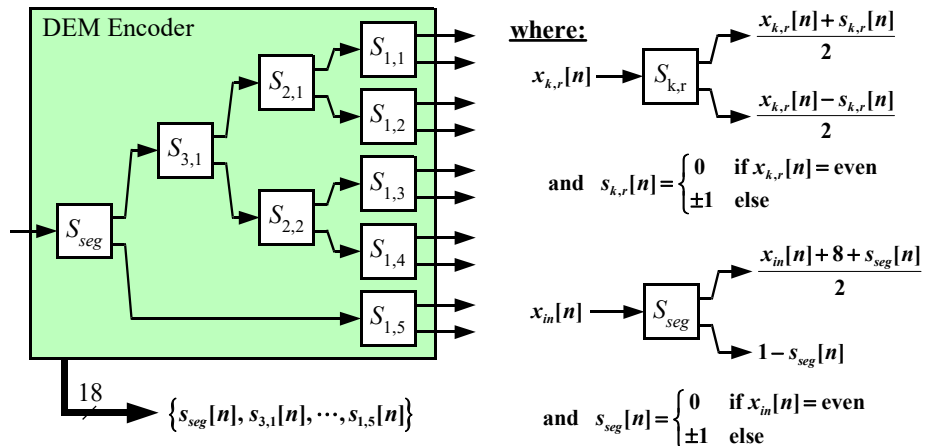
## DEM DAC Example for $x[n] = 1$



Chosen pseudo-randomly once per sample period

- $\alpha$  and  $\beta$  are independent of  $x[n]$  and pseudo-random choice
- $e_{DAC}[n]$  depends on pseudo-random choice

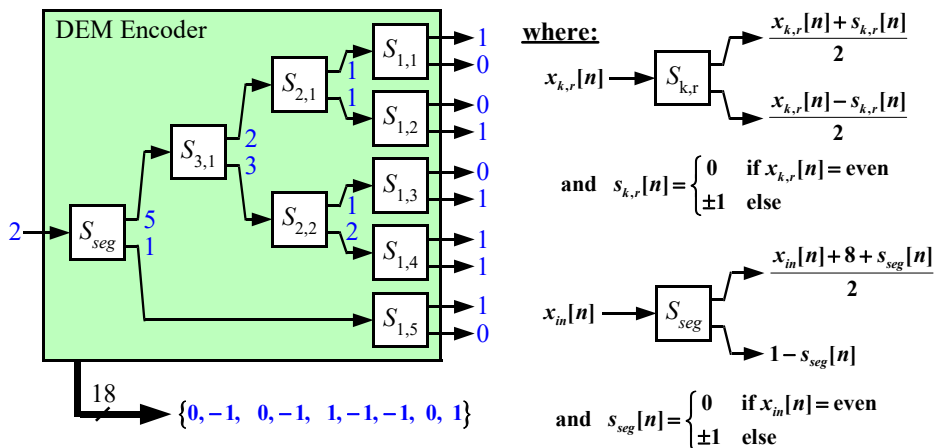
## The DEM Encoder: A Closer Look



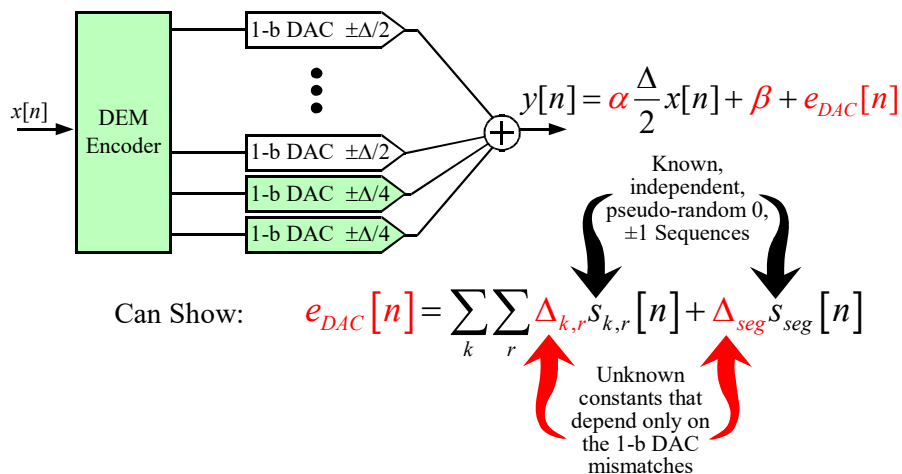
- $s_{seg}[n]$  and  $s_{j,k}[n]$  are independent pseudo-random 0,  $\pm 1$  sequences
- $s_{seg}[n]$  and  $s_{j,k}[n]$  are known by the digital logic

## The DEM Encoder: Example

One example set of choices for  $x[n] = 2$ :



## Structure of the DAC Noise

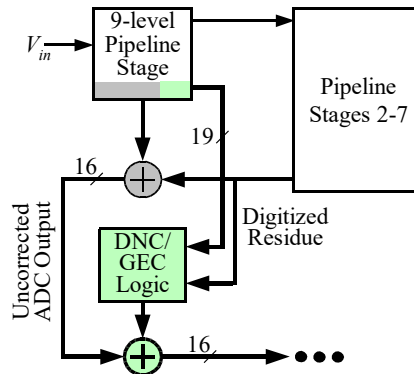


$e_{DAC}[n]$  is like a spread spectrum signal:

- $\Delta_{k,r}$  and  $\Delta_{seg}$  are the *unknown* (constant) “message signals”
- $s_{k,r}[n]$  and  $s_{seg}[n]$  are the *known* “spreading codes”

## The DNC Technique

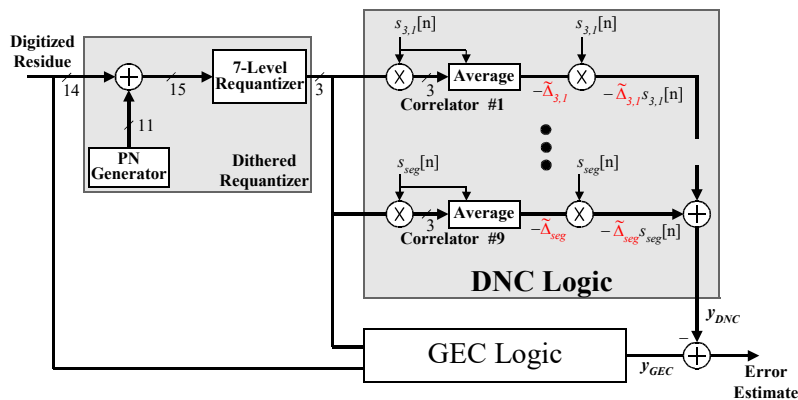
The DAC noise directly corrupts the uncorrected ADC output:



The DNC logic is a spread spectrum “receiver” that:

- correlates the *digitized residue* against  $s_{k,r}[n]$  and  $s_{seg}[n]$  to estimate  $\Delta_{k,r}$  and  $\Delta_{seg}$
- uses the DAC noise equation to cancel  $e_{DAC}[n]$

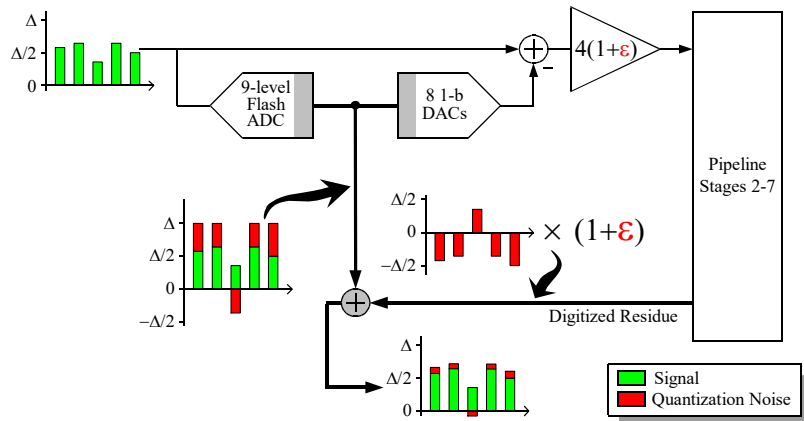
## First Stage Calibration Logic - DNC



- 9 simple spread-spectrum “receivers”
- Requantization:
  - reduces DNC logic size
  - dithered to avoid corrupting correlations

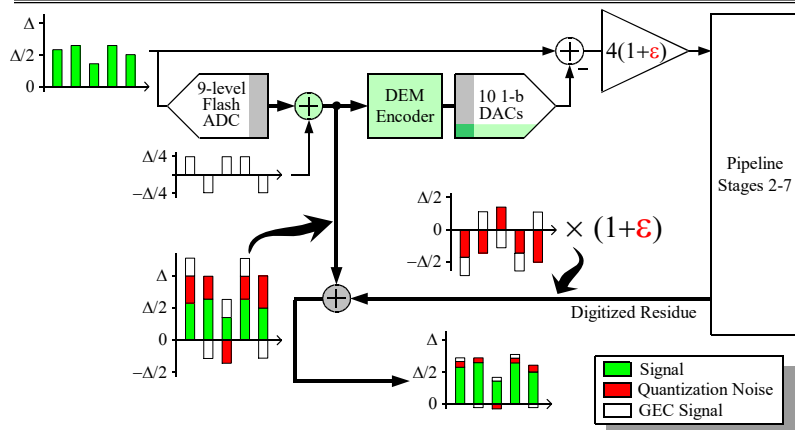
## Interstage Gain Error

### Conventional PADC:



- $\epsilon$  = interstage gain error
- Causes imperfect cancellation of ADC quantization noise
- Reduces SFDR and SNDR

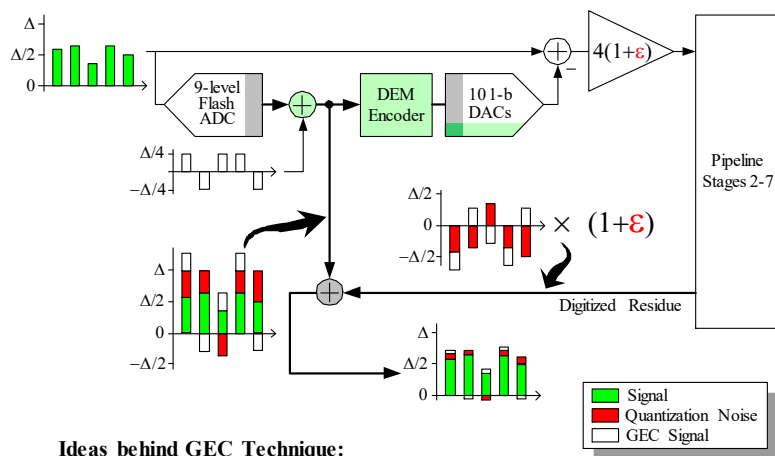
### The GEC Technique (1)



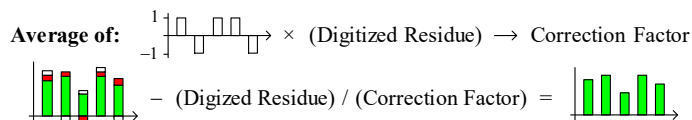
- A pseudo-random  $\pm\Delta/4$  sequence is introduced to the DAC path
- It occupies a portion of error headroom created by redundancy
- It follows the same path and sees the same gain as the quantization noise



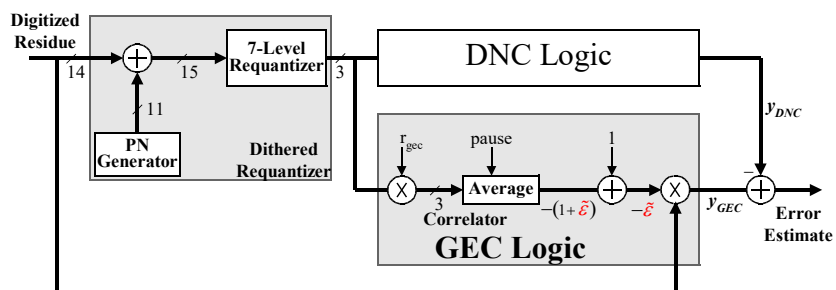
## The GEC Technique (2)



**Ideas behind GEC Technique:**



## First Stage Calibration Logic -GEC

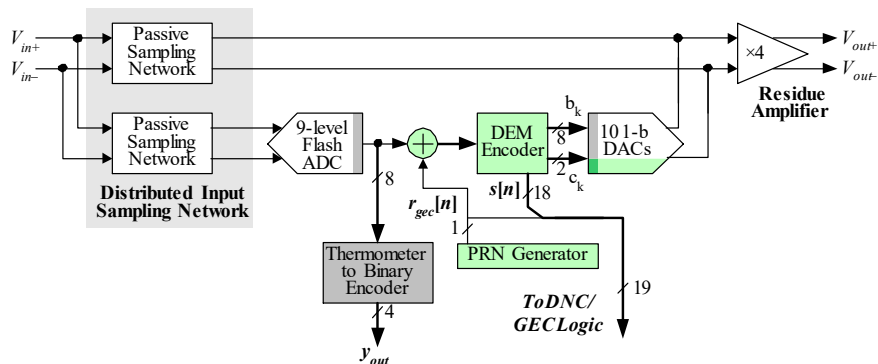


**Instead of dividing the digitized residue by the gain estimate:**

- a linear Taylor series approximation is used:  $\frac{1}{(1+\epsilon)} \approx 1-\epsilon$
- the resulting correction signal is added directly to output

**Any linear contribution to gain error is corrected!**

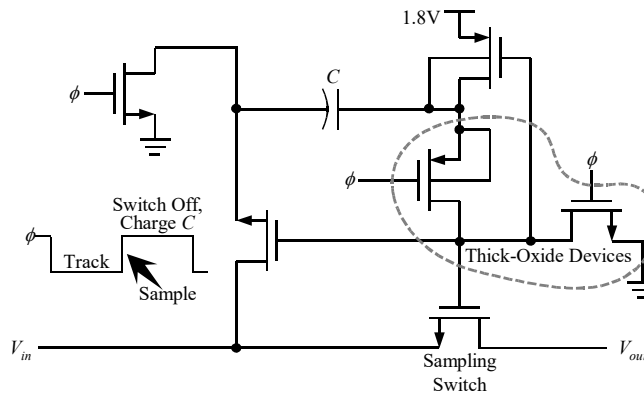
## Circuit-Level Details



- Distributed input sampling<sup>4</sup>
- Separate input and DAC sampling capacitors
- DNC&GEC => no special attention to cap matching

4. I. Mehr and L. Singer, *IEEE Journal of Solid State Circuits*, March 2000

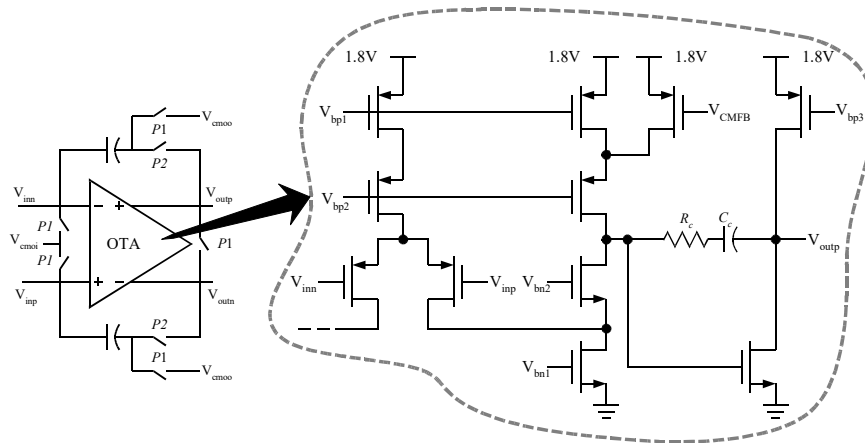
## Bootstrapped Switch Circuitry



- **Modified version of circuitry presented in [5]**
  - Thick-oxide devices to avoid exceeding technology limits
- **Uses a single 1.8V clock**

5. M. Dessouky and A. Kaiser, *IEE Electronics Letters*, January 1999

## Residue Amplifier (1)



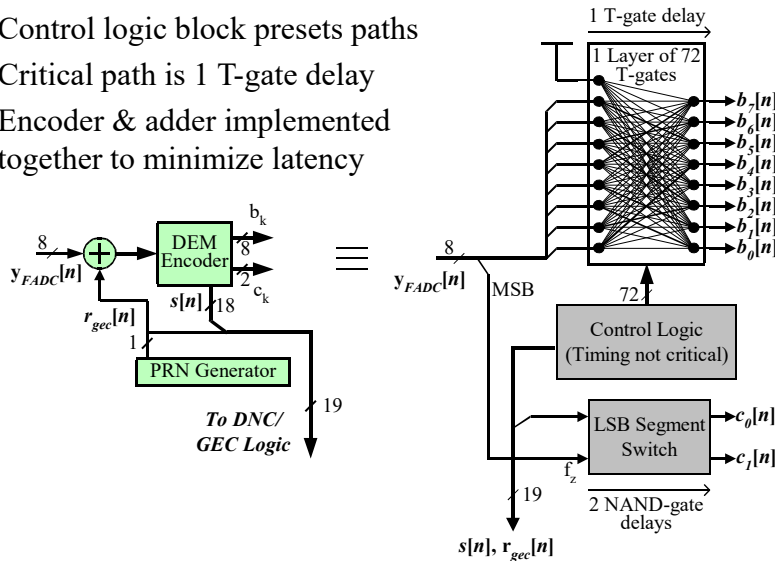
- Closed loop gain of 4
- Two-stages for high gain and wide output swing

## Residue Amplifier (2)

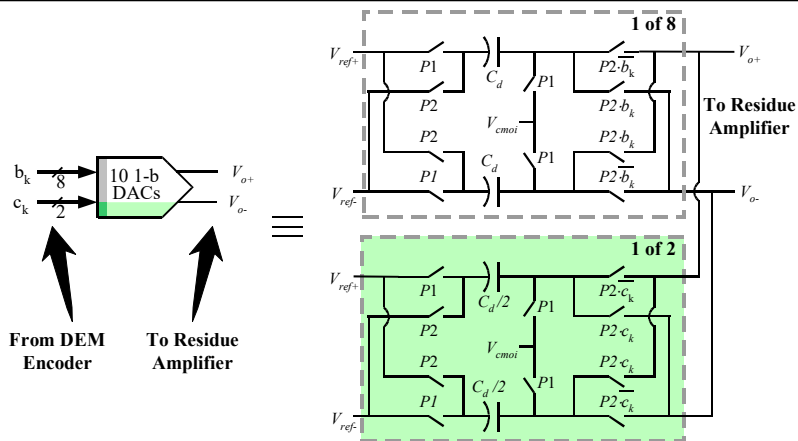
- **Conventional PADC:**
  - Open-loop gain requirement  $>100\text{dB}$
  - Gain-boosting is typically required
  - Simulated gain:  $>125\text{dB}$  with gain-boosting,  $85\text{dB}$  without
- **Prototype IC:**
  - Gain-boosting with enable/disable circuitry is included
  - As expected, measured PADC performance with GEC enabled and gain-boosting disabled does not change!
- **Scaled down once and used in the remaining stages without further scaling**

## DEM Encoder and GEC Adder Implementation

- Control logic block presets paths
- Critical path is 1 T-gate delay
- Encoder & adder implemented together to minimize latency



## DAC Sampling Network

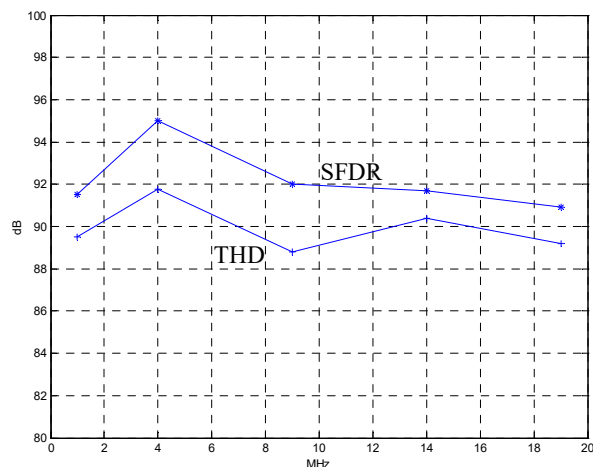


- 10 1-b DACs:
  - 8 step-size  $\Delta$
  - 2 step-size  $\Delta/2$
- References are “double sampled”
  - Capacitor sizes halved
  - Reduces kT/C noise

## Process, Layout and Packaging Overview

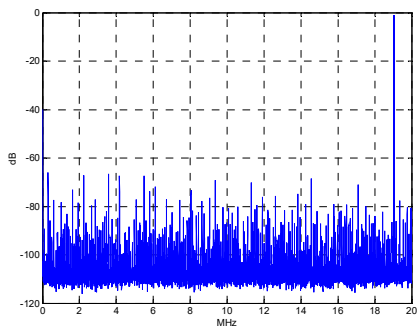
- **Process**
  - 0.18 $\mu$ m CMOS
  - MiM capacitors, deep Nwells, thick-oxide devices, low- $V_T$  devices
- **Layout**
  - Deep Nwells and multiple supply domains
  - No special attention to capacitor matching
  - ESD protection circuitry on all pads
- **Packaging**
  - 56-pin QFN package with exposed die paddle
  - Down-bonding of all grounds to exposed paddle
  - Double-bonding of critical supply pins

## Measured SFDR and THD vs. Input Frequency



- DNC and GEC enabled

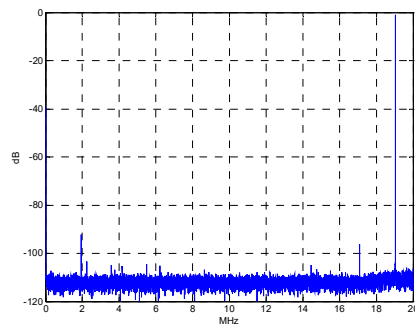
## Measured PSD with a 19 MHz Input



With DNC and GEC disabled

SFDR 64.8 dB

SNDR 54.7 dB

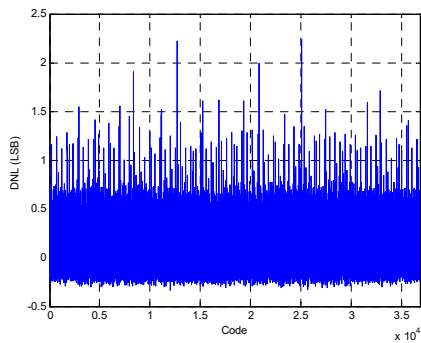


With DNC and GEC enabled

SFDR 90.9 dB

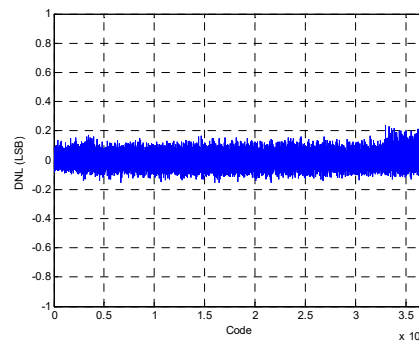
SNDR 71.6 dB

## Measured DNL ( $f_{in} = 1$ MHz)



With DNC and GEC disabled

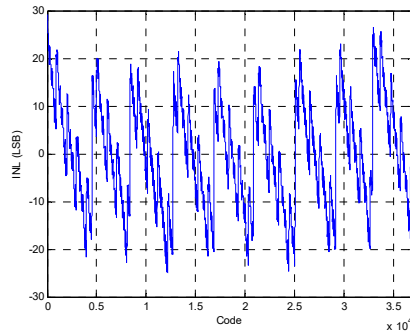
DNL = 2.3 LSB



With DNC and GEC enabled

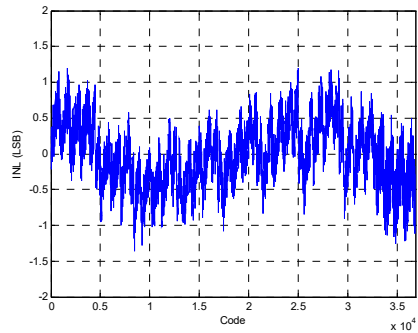
DNL = 0.25 LSB

## Measured INL ( $f_{in} = 1 \text{ MHz}$ )



With DNC and GEC disabled

INL = 25 LSB



With DNC and GEC enabled

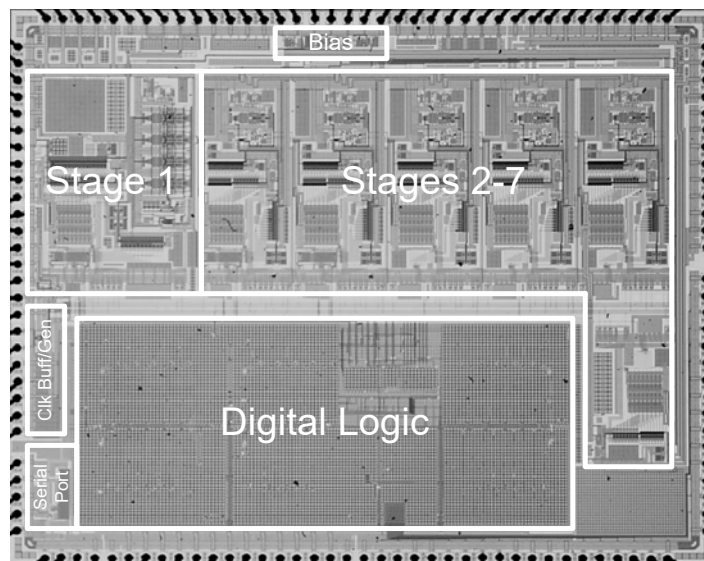
INL = 1.5 LSB

## Fabrication and Measurement Summary

Resolution	15 b
Sample Rate	40 MHz
Input Voltage Range	2.25 V <sub>p-p</sub> differential
SFDR	90 dB
THD	88 dB
Peak SNR	72 dB
DNL	0.25 LSB
INL	1.5 LSB
SFDR Improvement with DNC and GEC enabled	> 20 dB
SNDR Improvement with DNC and GEC enabled	> 12 dB
Total Power	400 mW
Analog Power	343 mW (1.8 V)
Digital Power	51 mW (2.1 V)
Output Drivers Power	6 mW (1.8 V)
Technology	0.18μm 1P6M CMOS
Die Size	4mm x 5mm (including pads)
Package	56-Pin QFN with ground downbonding

## Die Photo

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## Conclusion

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- The silicon implementation of two digital signal processing background calibration techniques has been presented
  - DNC to compensate for DAC mismatch noise
  - GEC to compensate for interstage gain errors
- Together they drastically reduce analog circuit requirements required to achieve high performance
- They have been shown to be enabling components in a high-resolution pipelined ADC



## Acknowledgements

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- The authors are grateful to **Erica Poole** for digital schematic capture and verification, **Sudhakar Pamarti** and **Ashok Swaminathan** for digital layout and technical advice, **Eric Fogleman** for technical advice, and **Andrea Panigada** for test board design and technical advice.